

0000 00 (00) 000000 0 00 IC 0000 000000.

00 BEST 000,

00 00

00 : 0000 0000 0000 / computer / mobile 00 / 00 00 SMD IC BGA IC 00000 0 000000 0000 00 0000 0 00
00000 0 00 00 00 00.

00 00000

B

E

S

T

-

7

5

0

90

%

7

:

00

%

/

0

70

%

0

:0

-

2

2

9

°

C

2
5
1
4
5
7
0
m
:
0
0
0
0
0
0
:
8
9
0
5
±
1
%
5
0
0
0
C
N
g
W
p
c

SOLDER PASTE

Lead-free High temperature



500g

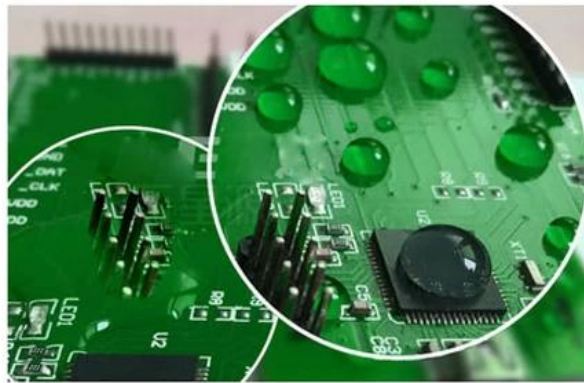
Low residue / Rapid welding / lead free / Solder spot bright / Ag

Product Usage

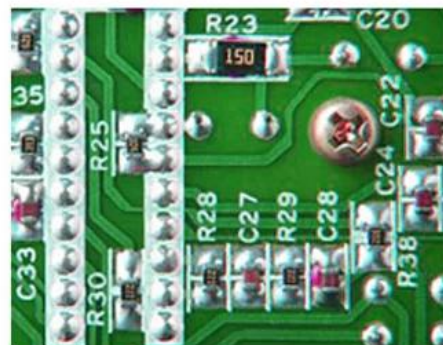
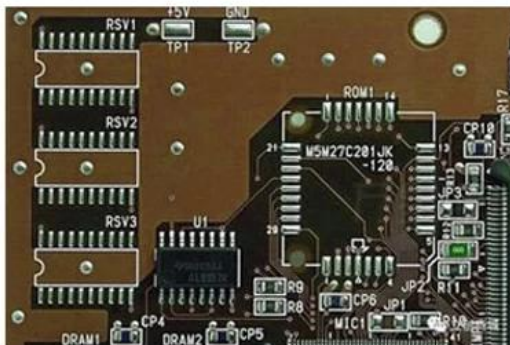


MODEL	BST-705
SHELF LIFE	6 months
INGREDIENT	Sn99/Ag0.3/Cu0.7
WEIGHT	500g
MELTING POINT	217°C

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue

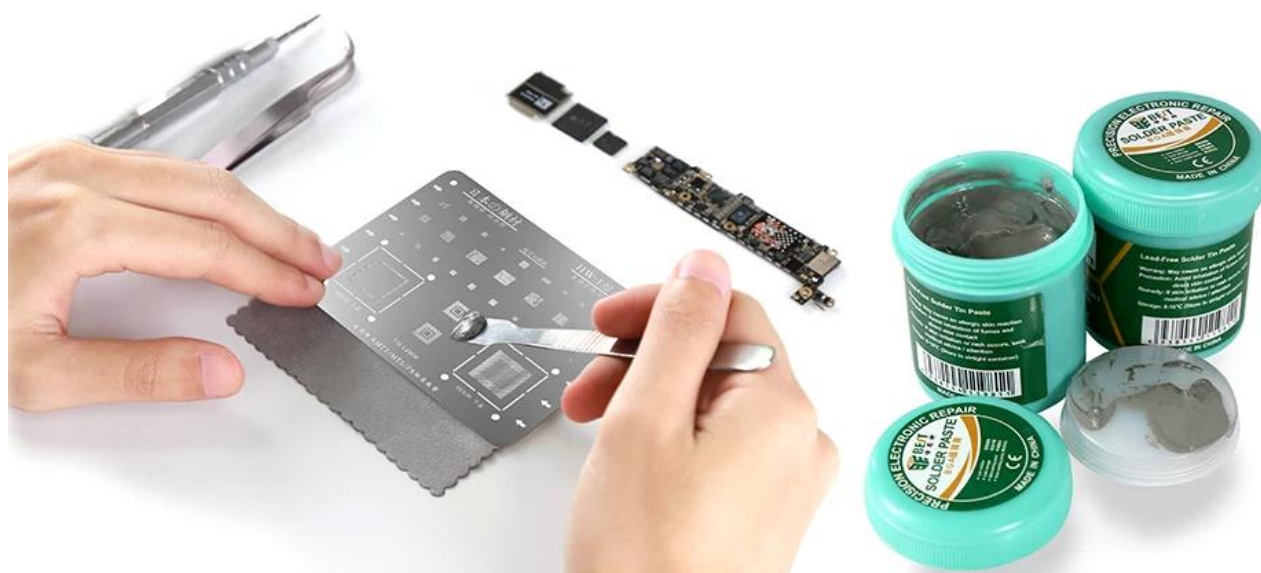


Welding requirements for a wide range of products



TESTING EFFECT

UNIFORM SOLDER JOINT
MEDIUM TEMPERATURE MELTING POINT



PRODUCT SIZE



63.0MM



52MM

75MM

